

## **AMENDMENTS TO THE SPECIFICATION**

Please amend the specification as follows:

Please amend the paragraph beginning at page 1, line 12 as follows:

Unlike semiconductors, [[As]] many micro-machines or micro-electromechanical-system (MEMS) devices have a fragile structure due to inclusion of a movable member in a chip, if they were, unlike semiconductors, which make it advantageous for them to be sealed before being forwarded to a dicing process, it would be advantageous. An attempt has been made to perform packaging during a wafer machining process in the past.

Please amend the paragraph beginning at page 5, line 13 as follows:

~~Chips each of which has a size of, for example, 5-mm-square and has MEMS members formed therein, that is, an MEMS device formed therein is defined on a silicon substrate 1.~~ Silicon substrate 1 may have defined thereon a plurality of chips, each chip having a size of, for example, 5-mm-square and having a MEMS member, or MEMS device, formed therein. A quartz substrate 2 serving as a sealing member, located on the silicon substrate 1, has, as shown in Fig. 2A and 2B, the same shape as this silicon substrate. The quartz substrate 2 has recesses 21, each of which has a size of 5-mm-square, formed therein for fear the quartz substrate may interfere with the MEMS components in the chips arranged on the silicon substrate 1. Moreover, alignment marks 22 to 25 are inscribed on the quartz substrate 2. If the side of the silicon substrate 1 to be

joined to the quartz substrate is higher than the tops of the MEMS components, that is, if the quartz substrate will not interfere with the MEMS components, the recesses 21 need not be formed in the quartz substrate. Moreover, a light shielding material 26 is applied to the internal surfaces of the recesses.